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FDMS86183

N-Channel Shielded Gate PowerTrench® MOSFET **100 V, 51 A, 12.8 m**Ω

Features

- Shielded Gate MOSFET Technology
- Max $r_{DS(on)} = 12.8 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 16 \text{ A}$
- Max $r_{DS(on)}$ = 34.6 m Ω at V_{GS} = 6 V, I_D = 8 A
- 50% Lower Qrr than Other MOSFET Suppliers
- Lowers Switching Noise/EMI
- MSL1 Robust Package Design
- 100% UIL Tested
- RoHS Compliant

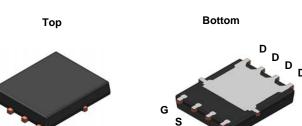
General Description

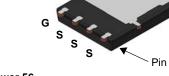
This N-Channel MV MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized to minimize on-state resistance and yet maintain superior switching performance with best in class soft body diode.

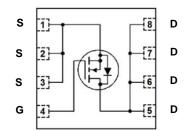
Applications

- Primary DC-DC MOSFET
- Synchronous Rectifier in DC-DC and AC-DC
- Motor Drive
- Solar









Power 56

MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted.

Symbol	Parame	ter		Ratings	Units
V _{DS}	Drain to Source Voltage			100	V
V_{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous	T _C = 25 °C	(Note 5)	51	
	-Continuous	T _C = 100 °C	(Note 5)	32	^
^I D	-Continuous	T _A = 25 °C	(Note 1a)	10	Α
	-Pulsed		(Note 4)	187	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	96	mJ
В	Power Dissipation	T _C = 25 °C		63	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	2.5	VV
T _J , T _{STG}	Operating and Storage Junction Temperat	ture Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS86183	FDMS86183	Power 56	13 "	12 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\Delta BV_{DSS} \over \Delta T_J$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		63		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μА
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 90 \mu A$	2.0	3.2	4.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 90 \mu A$, referenced to 25 °C		-9		mV/°C
r _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 16 A		9.9	12.8	
		$V_{GS} = 6 \text{ V}, I_D = 8 \text{ A}$		17	34.6	mΩ
, ,		V _{GS} = 10 V, I _D = 16 A, T _J = 125 °C		16.6	21.5	
g _{FS}	Forward Transconductance	V _{DS} = 5 V, I _D = 16 A		20		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz		1080	1515	pF
C _{oss}	Output Capacitance			646	905	pF
C _{rss}	Reverse Transfer Capacitance			10	15	pF
R _g	Gate Resistance		0.1	0.5	1.5	Ω

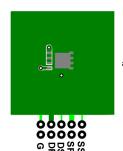
Switching Characteristics

t _{d(on)}	Turn-On Delay Time		11	20	ns
t _r	Rise Time	V _{DD} = 50 V, I _D = 16 A,	3	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	15	27	ns
t _f	Fall Time		3	10	ns
Q_g	Total Gate Charge	V _{GS} = 0 V to 10 V	15	21	nC
Qg	Total Gate Charge	$V_{GS} = 0 \text{ V to 6 V} V_{DD} = 50 \text{ V},$	10	14	nC
Q _{gs}	Gate to Source Charge	I _D = 16 A	5		nC
Q _{gd}	Gate to Drain "Miller" Charge		3.4		nC
Q _{oss}	Output Charge	V _{DD} = 50 V, V _{GS} = 0 V	43		nC

Drain-Source Diode Characteristics

V _{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2.1 \text{ A}$ (No	te 2)	0.7	1.2	V
	Source to Drain Diode Porward voltage	$V_{GS} = 0 \text{ V}, I_S = 16 \text{ A}$ (No	te 2)	0.9	1.3	v
t _{rr}	Reverse Recovery Time	I _E = 8 A, di/dt = 300 A/μs		22	36	ns
Q _{rr}	Reverse Recovery Charge	- 1 _F = 8 A, αι/αι = 300 A/μS		36	58	nC
t _{rr}	Reverse Recovery Time	I _F = 8 A, di/dt = 1000 A/μs		18	33	ns
Q_{rr}	Reverse Recovery Charge			79	127	nC

^{1.} R_{0JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0CA} is determined by the user's board design.



a) 50 °C/W when mounted on a 1 in² pad of 2 oz copper



b) 125 °C/W when mounted on a minimum pad of 2 oz copper.

^{2.} Pulse Test: Pulse Width < 300 µs, Duty cycle < 2.0%.
3. E_{AS} of 96 mJ is based on starting T₂ = 25 °C; N-ch: L = 3 mH, I_{AS} = 8 A, V_{DD} = 100 V, V_{GS} =10 V. 100% test at L = 0.3 mH, I_{AS} = 18 A.
4. Pulsed Id please refer to Fig 11 SOA graph for more details.
5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

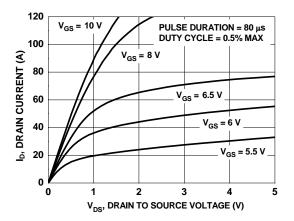


Figure 1. On-Region Characteristics

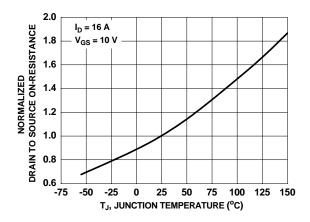


Figure 3. Normalized On-Resistance vs. Junction Temperature

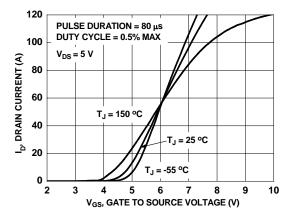


Figure 5. Transfer Characteristics

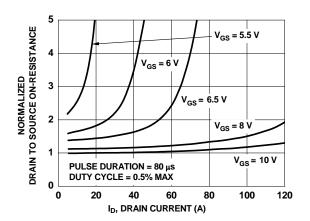


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

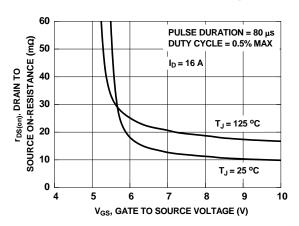


Figure 4. On-Resistance vs. Gate to Source Voltage

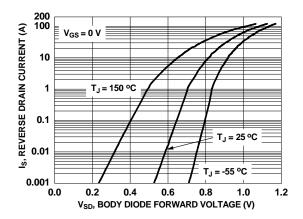


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

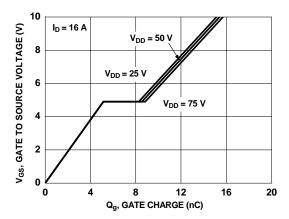


Figure 7. Gate Charge Characteristics

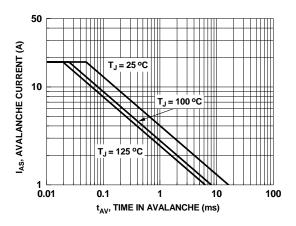


Figure 9. Unclamped Inductive Switching Capability

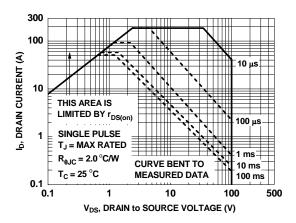


Figure 11. Forward Bias Safe Operating Area

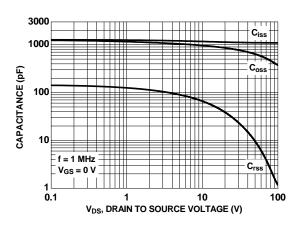


Figure 8. Capacitance vs. Drain to Source Voltage

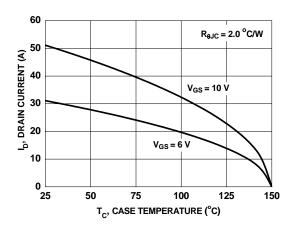


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

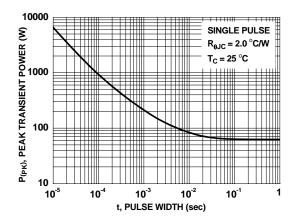


Figure 12. Single Pulse Maximum Power Dissipation



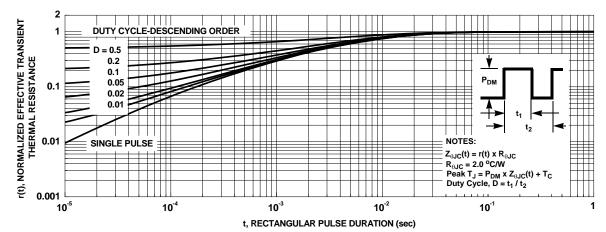
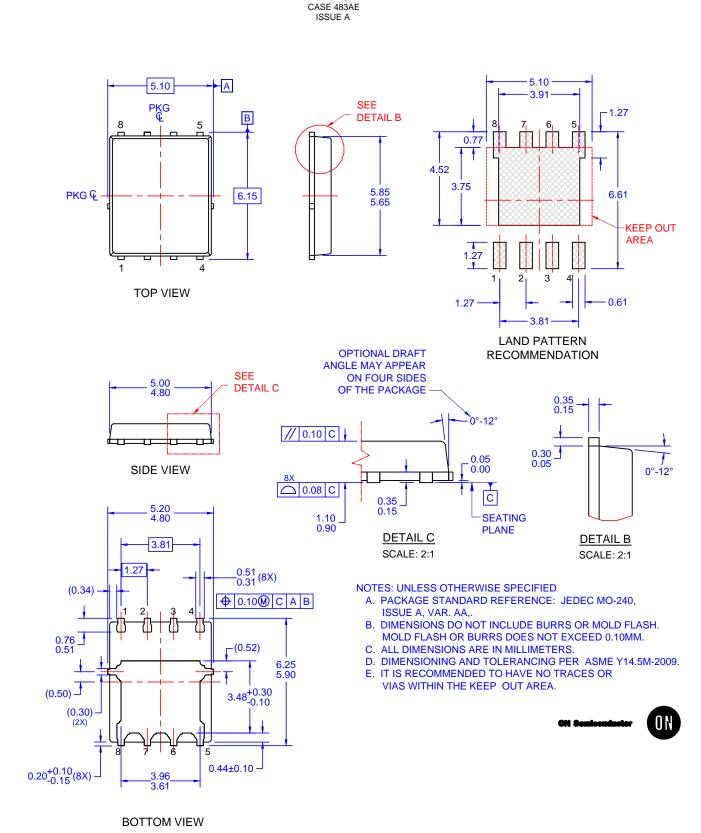


Figure 13. Junction-to-Case Transient Thermal Response Curve



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